

Somos[®] ProtoTherm[™] 12120

Stereolithography

A fast-building stereolithography material specifically designed to deliver high temperature resistance with exceptional surface finishing.

Somos[®] ProtoTherm 12120 stereolithography material is the excellent solution for applications requiring resistance to heat and humidity.

Somos[®] ProtoTherm 12120 excels at producing highly detailed, extremely accurate parts. The material is dimensionally stable when exposed to heat and humidity making it a good candidate for high temperature fluid flow analysis, functional prototypes, and limited run, non-critical end-use parts such as wiring harnesses and support connectors in electronic devices.



Key Benefits

- Extremely precise accuracy for small details
- Resistant to heat up to 250°F (121°C)
- Stable in high humidity environments

Ideal Applications

- High-temperature fluid flow analysis
- Functional prototypes requiring heat and humidity resistance
- High-detail parts
- Low volume connectors and harnesses for electronics

LIQUID PROPERTIES		OPTICAL PROPERTIES		
Appearance	Red	E _c	11.8 mJ/cm ²	[critical exposure]
Viscosity	~550 cps @ 30°C	D _p	6 mils	[slope of cure-depth vs. ln (E) curve]
Density	~1.15 g/cm ³ @ 25°C	E ₁₀	63 mJ/cm ²	exposure that gives 0.254 mm (.010 inch) thickness]

MECHANICAL PROPERTIES		UV POSTCURE		THERMAL POSTCURE	
ASTM Method	Property Description	Metric	Imperial	Metric	Imperial
D638M	Tensile Strength at Break	70.2 MPa	10.2 ksi	77 MPa	11.2 ksi
D638M	Elongation at Break	4%		4.5%	
D638M	Tensile Modulus	3,520 MPa	511 ksi	3,250 MPa	471 ksi
D790M	Flexural Strength	109 MPa	15.8 ksi	103 MPa	15 ksi
D2240	Flexural Modulus	3,320 MPa	482 ksi	3,060 MPa	444 ksi
D256A	Izod Impact (Notched)	12 J/m	0.22 ft-lb/in	17 J/m	0.32 ft-lb/in
D2240	Hardness (Shore D)	85		87	
D570-98	Water Absorption	0.37%		0.24%	

THERMAL/ELECTRICAL PROPERTIES		UV POSTCURE		THERMAL POSTCURE	
ASTM Method	Property Description	Metric	Imperial	Metric	Imperial
E831-05	TC.T.E. -40–0°C (-40–32°F)	58.1 $\mu\text{m}/\text{m}^\circ\text{C}$	32 $\mu\text{in}/\text{in}^\circ\text{F}$	77 MPa	11.2 ksi
E831-05	C.T.E. 0–50°C (32–122°F)	80.7 $\mu\text{m}/\text{m}^\circ\text{C}$	45 $\mu\text{in}/\text{in}^\circ\text{F}$	3,250 MPa	471 ksi
E831-05	C.T.E. 50–100°C (122–212°F)	111.4 $\mu\text{m}/\text{m}^\circ\text{C}$	62 $\mu\text{in}/\text{in}^\circ\text{F}$	3,250 MPa	471 ksi
E831-05	C.T.E. 100–150°C (212–302°F)	136.1 $\mu\text{m}/\text{m}^\circ\text{C}$	76 $\mu\text{in}/\text{in}^\circ\text{F}$	103 MPa	15 ksi
D150-98	Dielectric Constant 60 Hz	4.14		3.89	
D150-98	Dielectric Constant 1 KHz	4.04		3.84	
D150-98	Dielectric Constant 1 MHz	3.81		3.53	
D149-97A	Dielectric Strength	15.5 kV/mm	393 V/mil	16.4 kV/mm	417 V/mil
E1545-00	Tg	74°C	165°F	111°C	232°F
D648	HDT @ 0.46 MPa (66 psi)	56.5°C	134°F	126.2°C	259°F
D648	HDT @ 1.81 MPa (264 psi)	51.9°C	125°F	110.7°C	231°F

These values may vary and depend on individual machine processing and post-curing practices.